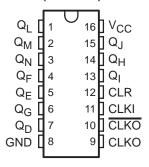
SN54HC4060, SN74HC4060 14-STAGE ASYNCHRONOUS BINARY COUNTERS AND OSCILLATORS

SCLS161D - DECEMBER 1982 - REVISED SEPTEMBER 2003

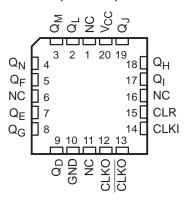
- Wide Operating Voltage Range of 2 V to 6 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max ICC
- Typical $t_{pd} = 14 \text{ ns}$

SN54HC4060 . . . J OR W PACKAGE SN74HC4060 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- ±4-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- Allow Design of Either RC- or **Crystal-Oscillator Circuits**

SN54HC4060 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'HC4060 devices consist of an oscillator section and 14 ripple-carry binary counter stages. The oscillator configuration allows design of either RC- or crystal-oscillator circuits. A high-to-low transition on the clock (CLKI) input increments the counter. A high level at the clear (CLR) input disables the oscillator (CLKO goes high and CLKO goes low) and resets the counter to zero (all Q outputs low).

ORDERING INFORMATION

TA	PACKA	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC4060N	SN74HC4060N
		Tube of 40	SN74HC4060D	
-40°C to 85°C	SOIC - D	Reel of 2500	SN74HC4060DR	HC4060
		Reel of 250	SN74HC4060DT	
	SOP - NS	Reel of 2000	SN74HC4060NSR	HC4060
	SSOP - DB	Reel of 2000	SN74HC4060DBR	HC4060
		Tube of 90	SN74HC4060PW	
	TSSOP - PW	Reel of 2000	SN74HC4060PWR	HC4060
		Reel of 250	SN74HC4060PWT	
	CDIP – J	Tube of 25	SNJ54HC4060J	SNJ54HC4060J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC4060W	SNJ54HC4060W
	LCCC – FK	Tube of 55	SNJ54HC4060FK	SNJ54HC4060FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



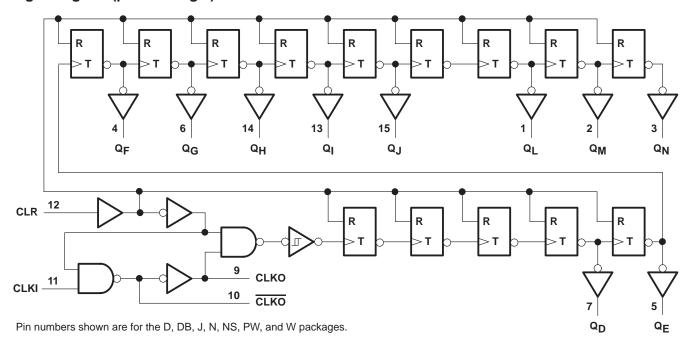
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE (each buffer)

	INPU	ITS	FUNCTION
CI	_K	CLR	FUNCTION
1	1	L	No change
		L	Advance to next stage
>	<	Н	All outputs L

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (se	e Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCC	c) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	·	±25 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package	73°C/W
	DB package	82°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{stq}		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54HC4060, SN74HC4060 14-STAGE ASYNCHRONOUS BINARY COUNTERS AND OSCILLATORS

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recommended operating conditions (see Note 3)

			SN	54HC40	60	SN	74HC40	60	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		V _{CC} = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		VCC = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		VCC = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					Т	A = 25°C	;	SN54H	C4060	SN74H0	C4060	
PAR	AMETER	TEST CO	NDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
				2 V	1.9	1.998		1.9		1.9		
	All outputs	VI = VIH or VIL,	$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
∨он				6 V	5.9	5.999		5.9		5.9		V
	O acceptance to	Mr. Mr. an Mr.	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
	Q outputs	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
				2 V		0.002	0.1		0.1		0.1	
	All outputs	VI = VIH or VIL,	$IOL = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL				6 V		0.001	0.1		0.1		0.1	V
	O acceptance to	Mr. Mr. an Mr.	I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
	Q outputs	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
П		$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc		$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci	·			2 V to 6 V		3	10		10		10	pF

SN54HC4060, SN74HC4060 14-STAGE ASYNCHRONOUS BINARY COUNTERS AND OSCILLATORS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			.,	T _A =	25°C	SN54H	C4060	SN74H	C4060		
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		5.5		3.7		4.3		
f _{Clock} Clock frequency			4.5 V		28		19		22	MHz	
			6 V		33		22		25		
			2 V	90		135		115			
		CLKI high or low	CLKI high or low	4.5 V	18		27		23		
	Dulas duration		6 V	15		23		20			
t _W	Pulse duration		2 V	90		135		115		ns	
		CLR high	4.5 V	18		27		23			
			6 V	15		23		20			
	·					240		200			
t _{su}	t _{SU} Setup time, CLR inactive before CLKI↓		4.5 V	32		48		40		ns	
			6 V	27		41		34			

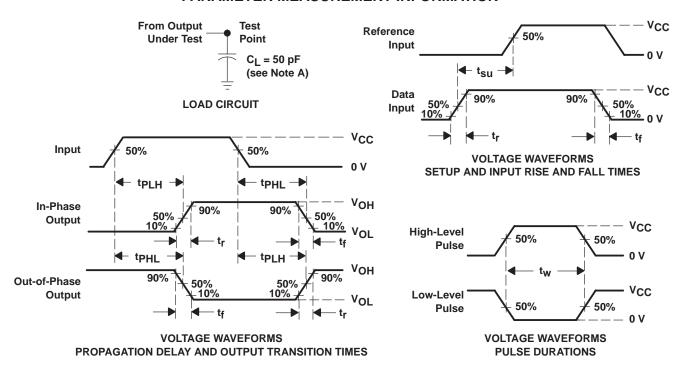
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

	FROM	то	,,	Τ _Δ	(= 25°C	;	SN54H	C4060	SN74H	C4060	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	5.5	10		3.7		4.3		
f _{max}			4.5 V	28	45		19		22		MHz
			6 V	33	53		22		25		
			2 V		240	490		735		615	
^t pd	CLKI	Q _D	4.5 V		58	98		147		123	ns
·			6 V		42	83		125		105	
			2 V		66	140		210		175	
^t PHL	CLR	Any Q	4.5 V		18	28		42		35	ns
			6 V		14	24		36		30	
			2 V		28	75		110		95	
t _t		Any	4.5 V		8	15		22		19	ns
			6 V		6	30		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	88	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_\Gamma = 6 \ ns$, $t_f = 6 \ ns$.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

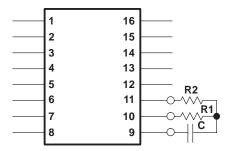
Figure 1. Load Circuit and Voltage Waveforms

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CONNECTING AN RC-OSCILLATOR CIRCUIT TO THE 'HC4060 DEVICES

The 'HC4060 devices consist of an oscillator section and 14 ripple-carry binary counter stages. The oscillator configuration allows design of either RC- or crystal-oscillator circuits.

When an RC-oscillator circuit is implemented, two resistors and a capacitor are required. The components are attached to the terminals as shown:



To determine the values of capacitance and resistance necessary to obtain a specific oscillator frequency (f), use this formula:

$$f = \frac{1}{2(R1)(C)\left(\frac{0.405 R2}{R1 + R2} + 0.693\right)}$$

If R2 > > R1 (i.e., R2 = 10R1), the above formula simplifies to:

$$f = \frac{0.455}{RC}$$

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
SN54HC4060FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC 4060FK
SN54HC4060FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC 4060FK
SN74HC4060D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC4060
SN74HC4060DBR	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060DBR.A	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060DT	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC4060
SN74HC4060N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC4060N
SN74HC4060N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC4060N
SN74HC4060NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060NSRE4	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060PW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC4060
SN74HC4060PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060PWRG4	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060PWRG4.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC4060
SN74HC4060PWT	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC4060

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

PACKAGE OPTION ADDENDUM

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(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54HC4060, SN74HC4060:

Catalog: SN74HC4060

Automotive: SN74HC4060-Q1, SN74HC4060-Q1

Military: SN54HC4060

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC4060DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74HC4060DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4060NSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74HC4060PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC4060PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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*All dimensions are nominal

7 till dillitoriolorio di o mominar							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC4060DBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74HC4060DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74HC4060NSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74HC4060PWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74HC4060PWRG4	TSSOP	PW	16	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN54HC4060FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SN54HC4060FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74HC4060N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC4060N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC4060N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC4060N.A	N	PDIP	16	25	506	13.97	11230	4.32



SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-150.





- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.







- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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